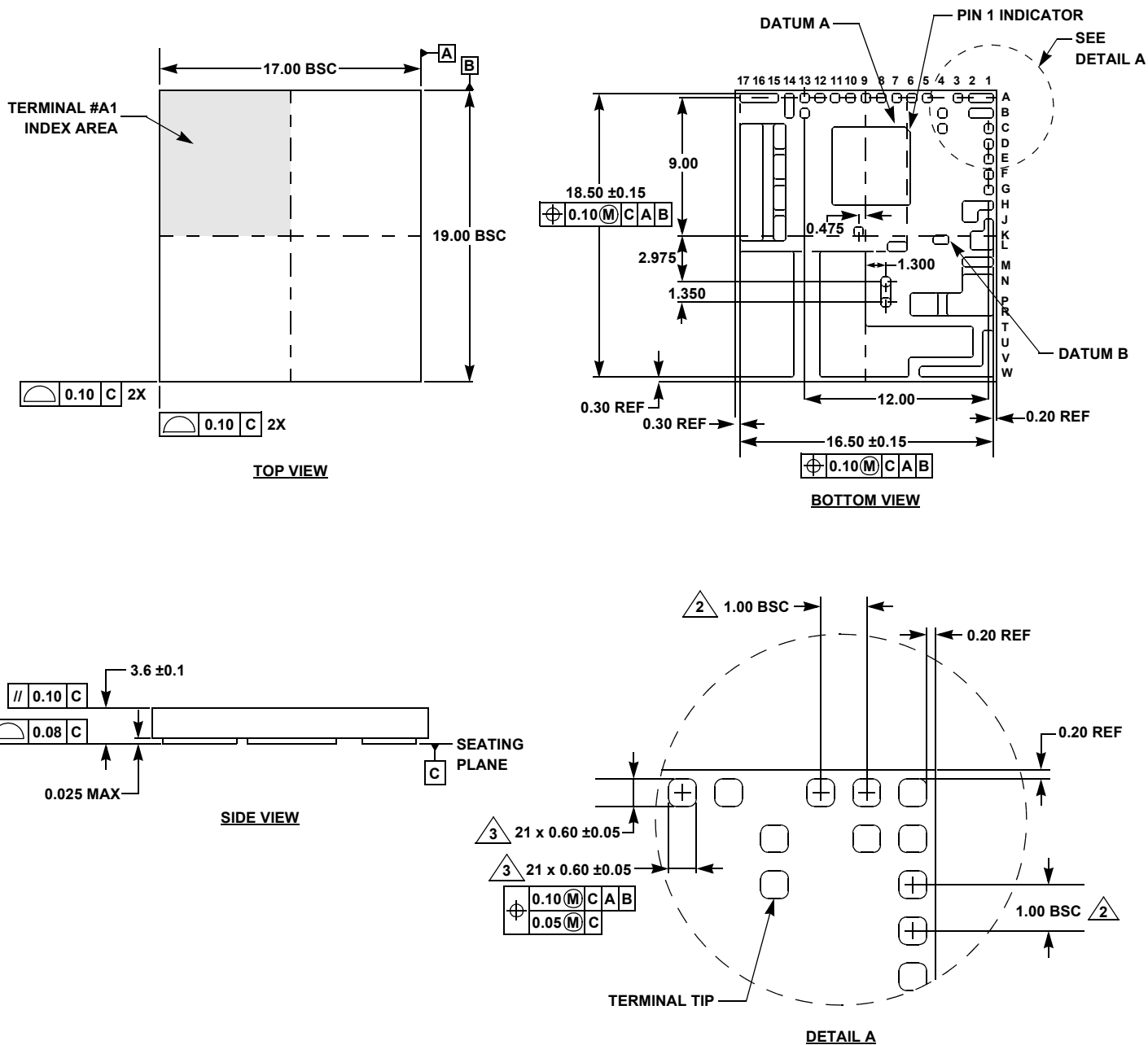


Package Outline Drawing

Y41.17x19

41 I/O 17.0mm x 19.0mmx3.6mm HDA MODULE

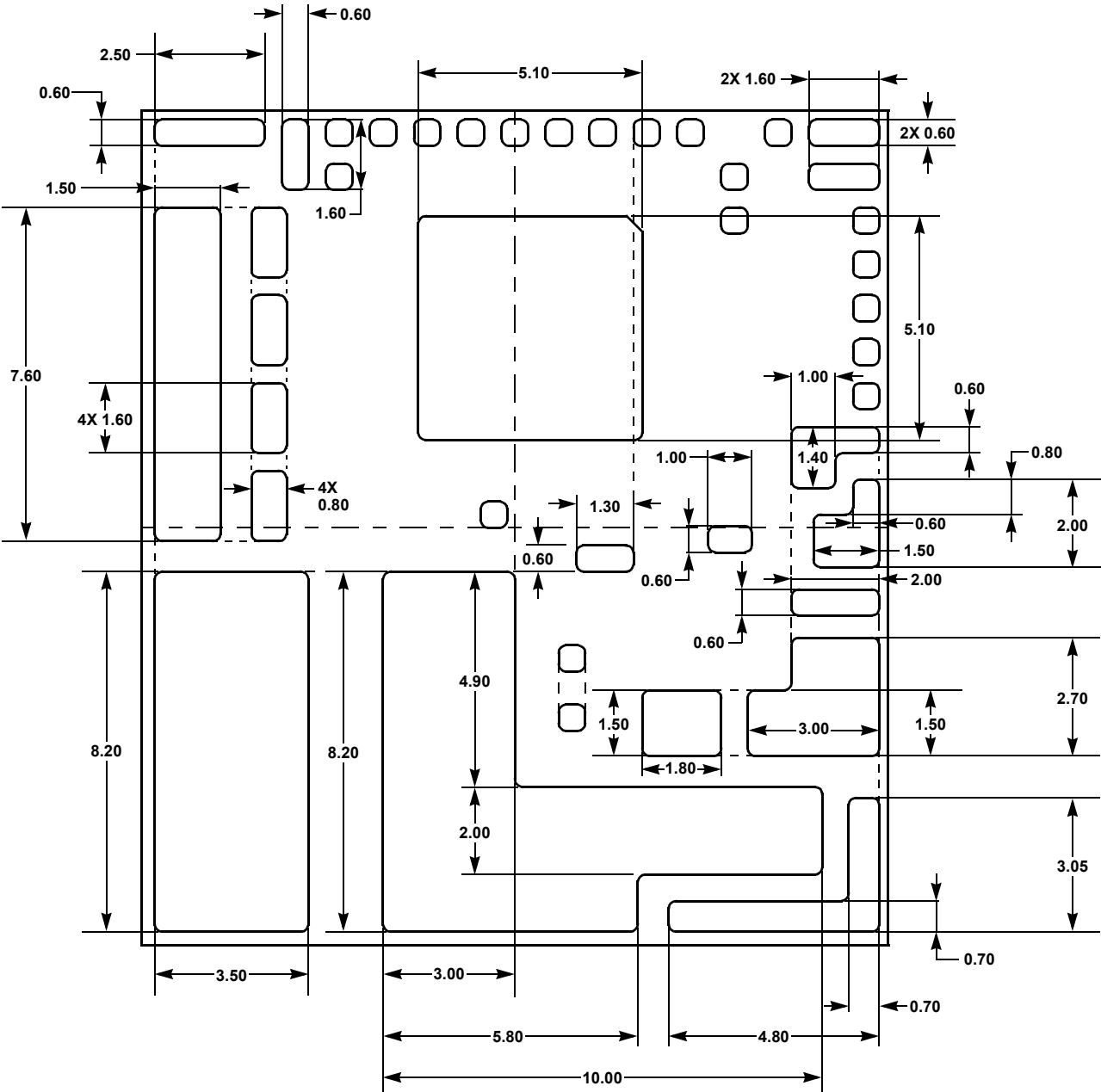
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NOTES:

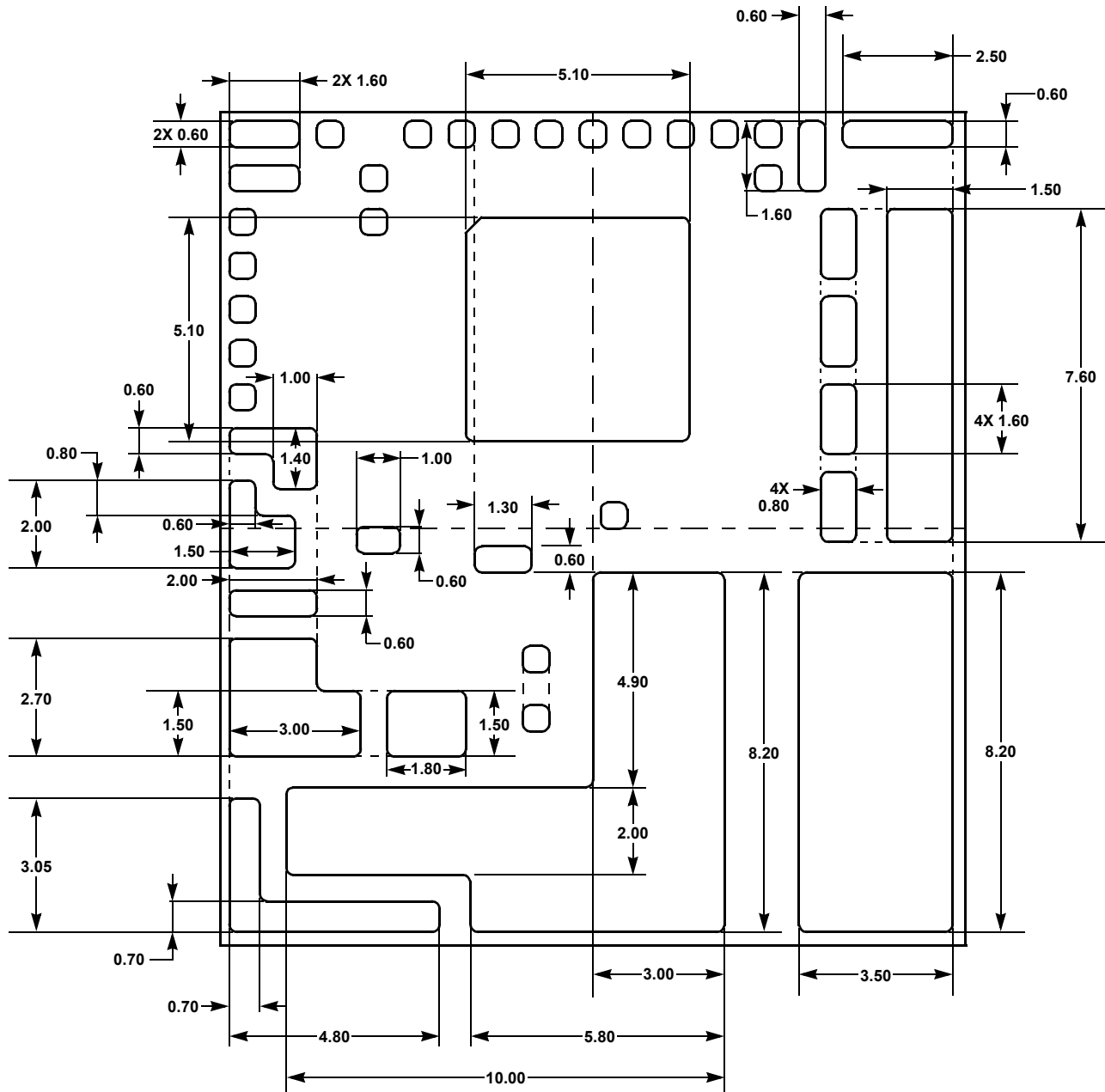
- All dimensions are in millimeters.
- △2 Represents the basic land grid pitch.
- △3 The total number of I/O (excluding dummy pads).
- Unless otherwise specified, tolerance: decimal ±0.10.
- Dimensioning and tolerancing per ASME Y14.M-2009.
- The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.

Plastic Packages for Integrated Circuits



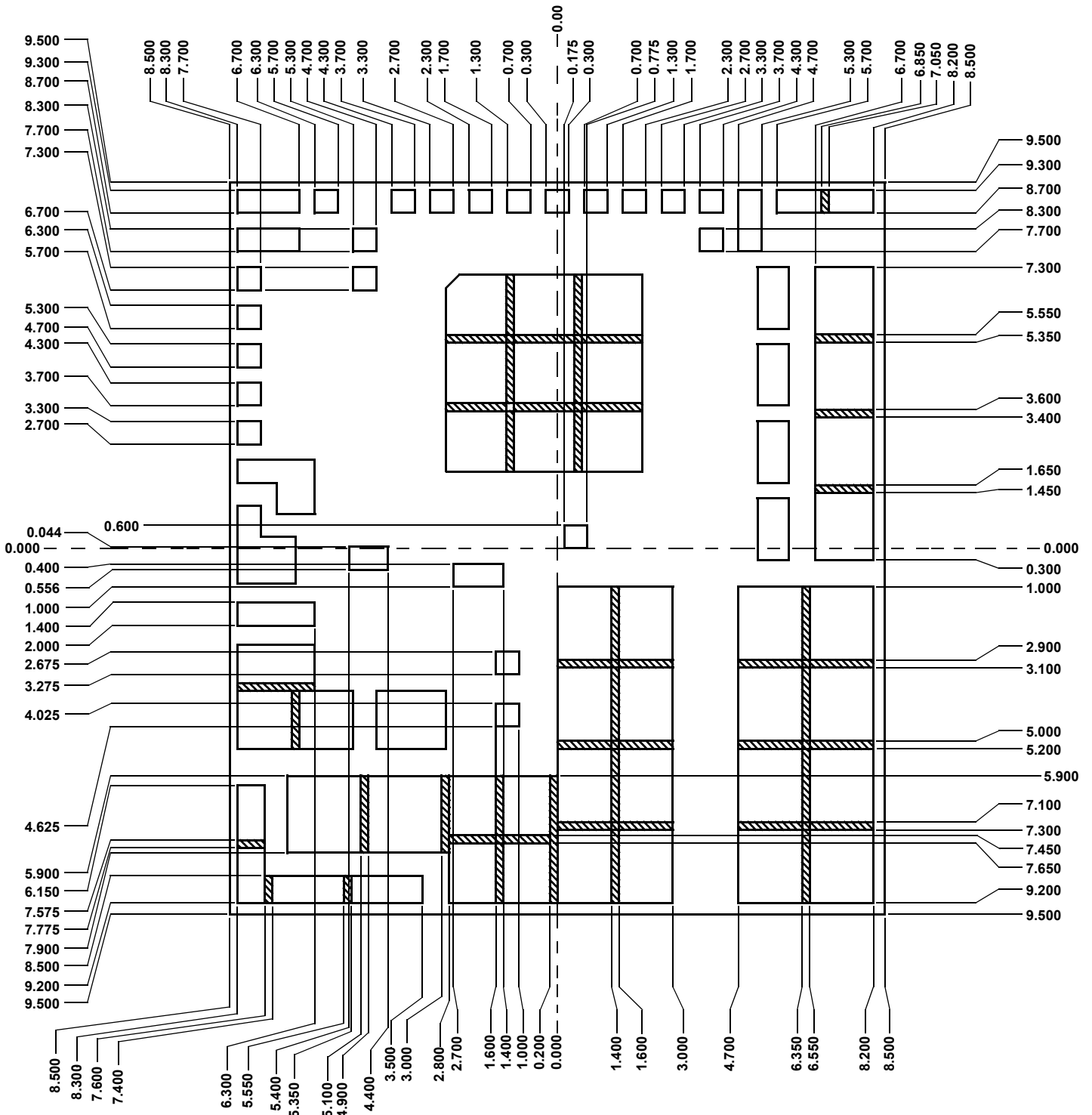
**SIZE DETAILS FOR THE 16 EXPOSED DAPS
BOTTOM VIEW**

Plastic Packages for Integrated Circuits



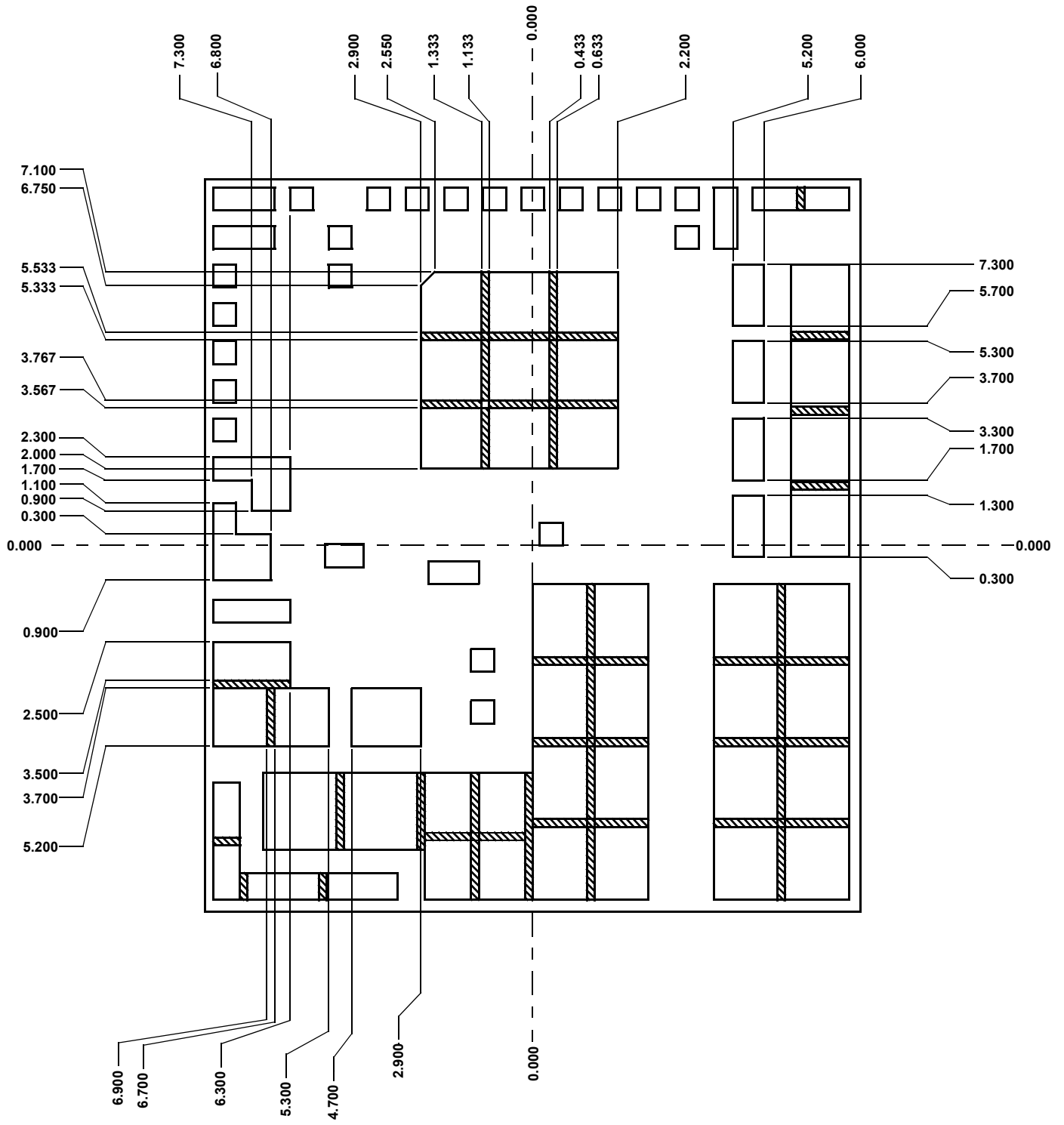
SIZE DETAILS FOR THE 16 EXPOSED DAPS
TOP VIEW

Plastic Packages for Integrated Circuits



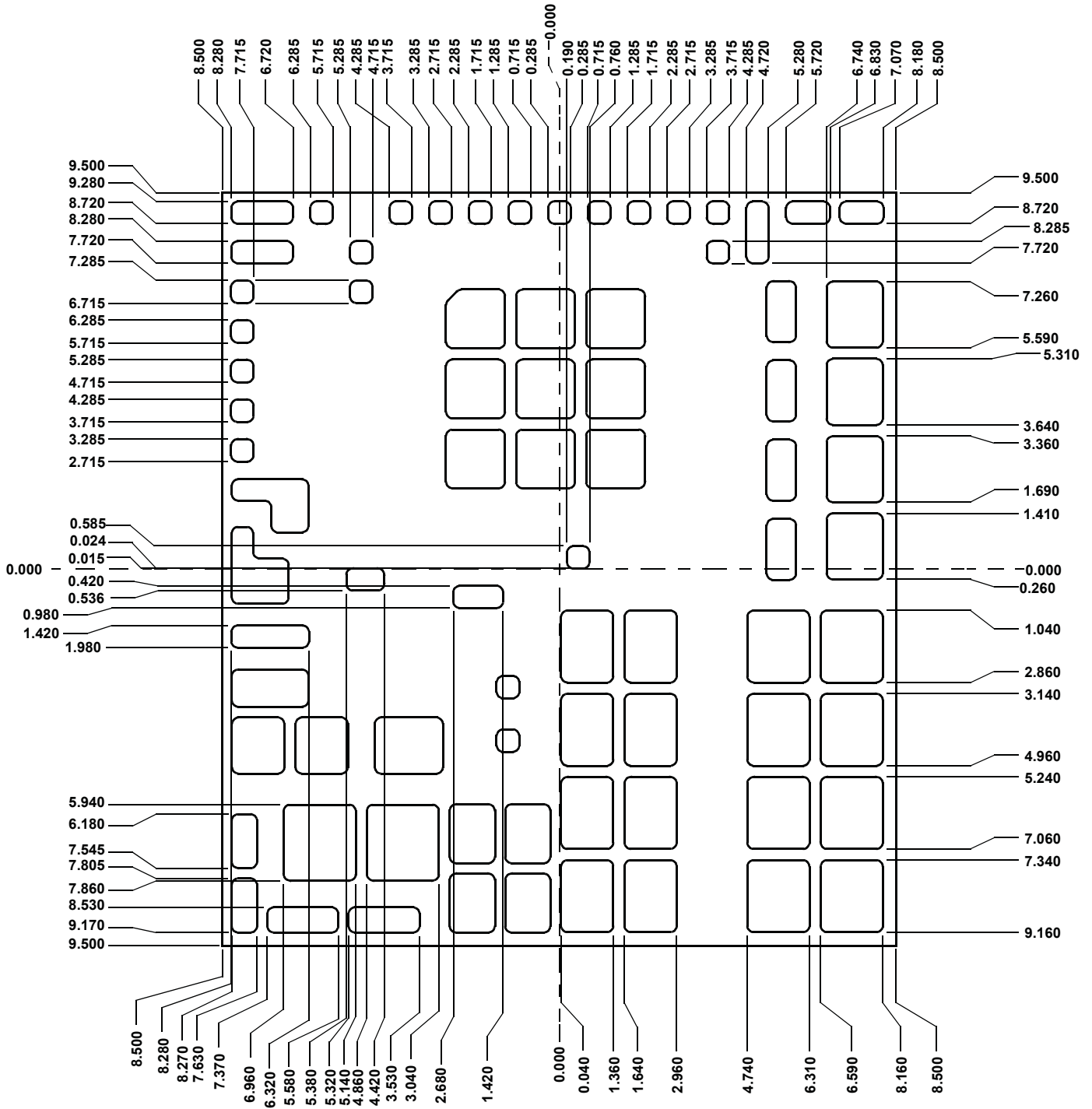
RECOMMENDED SOLDER MASK DEFINED PCB LAND PATTERN (1)
TOP VIEW

Plastic Packages for Integrated Circuits



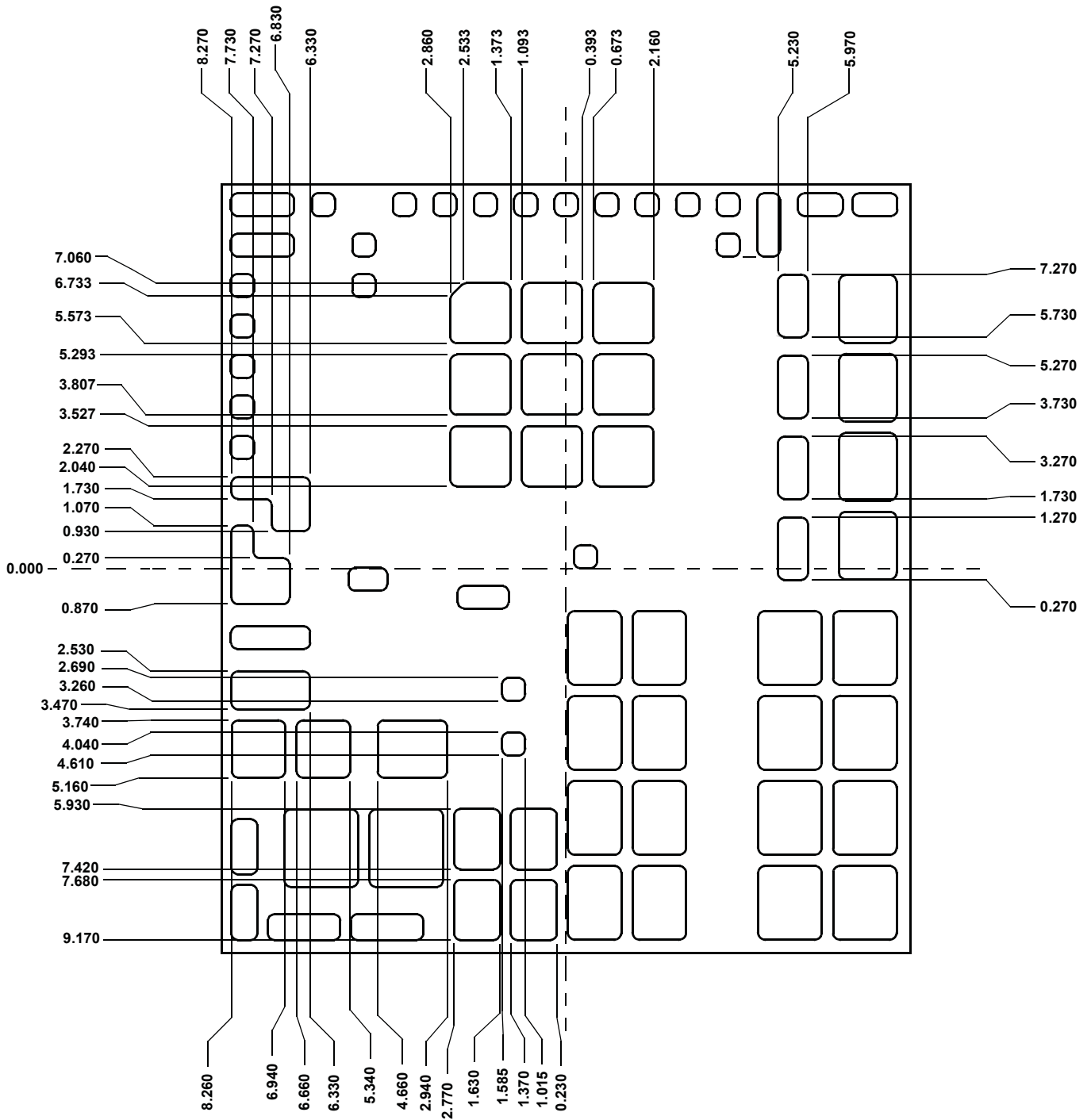
RECOMMENDED SOLDER MASK DEFINED PCB LAND PATTERN (2)
TOP VIEW

Plastic Packages for Integrated Circuits



RECOMMENDED STENCIL PATTERN (90% PASTE TO PAD) (1)
TOP VIEW

Plastic Packages for Integrated Circuits



RECOMMENDED STENCIL PATTERN (90% PASTE TO PAD) (2)
TOP VIEW